









# PRODUCT DATASHEET





- ► Ceramic High Power
- ➤ 3535 1.5t Series
- ► UV 407nm/275nm

N0D52S94Z





# **3535 1.5t Series**





Release Date: 24 September 2020 Version: A1.0

## **FEATURES:**

- Package: Ceramic SMT Package with Glass Lens
- Forward Current: 20mA
- Forward Voltage (typ.): 3.0/6.0V\*
- Radiant Power (typ.): 18.5/1.9mW@20mA
- Colour: Ultraviolet (UVA+UVC)
- Wavelength: 407/275nm
- Viewing angle: 120°
- Materials:
  - Die: InGaN/InGaN
  - Resin: Glass (Water Clear)
  - L/F: Ceramic
- Operating Temperature: -10~+30°C Storage Temperature: -10~+65°C
- **Grouping parameters:** 
  - Forward Voltage
  - **Radiant Power**
  - Peak Wavelength
- Soldering methods: IR Reflow soldering
- MSL: Level 3 according to J-STD020
- Packing: 12mm tape with min. 100pcs/reel, ø180mm (7")

## **APPLICATIONS:**

- **Industrial Curing**
- Counterfeit Detection
- Medical Device
- Fluorochemistry
- **Bacterial Identification**
- Cosmetology
- Magnetic Particle Inspection
- Clean Room Inspection
- Mineralogy

<sup>\*</sup> in the order of UVA/UVC







## **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	I <sub>MAX</sub>	20/20*	mA
Pulse Current Width=100μs Duty 1/10	lР	30/30	mA
Reverse Voltage	V <sub>R</sub>	5	V
Reverse Current @5V	I <sub>R</sub>	10	μΑ
Junction Temperature	Tj	35	°C
Power Dissipation	R <sub>D</sub>	0.15	W
Operating Temperature	T <sub>OPR</sub>	-10~+30	°C
Storage Temperature	T <sub>STG</sub>	-10~+65	°C
Solder Temperature	TsoL	260 for 10sec	°C

<sup>\*</sup> in the order of UVA/UVC

# Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Offic	Condition
Forward Voltage	VF		3.0/6.0*		V	I <sub>F</sub> =20mA
Radiant Power	Po		18.5/1.9		mW	I <sub>F</sub> =20mA
Peak Wavelength	WP		407/275		nm	I <sub>F</sub> =20mA
Spectrum Half Width	Δλ		12.9/10.5		nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =20mA

<sup>1.</sup> Radiant Power ( $P_0$ )  $\pm 10\%$ , Forward Voltage ( $V_F$ )  $\pm 0.2V$ , Wavelength (nm)  $\pm 2$ nm

<sup>2. \*</sup> in the order of UVA/UVC

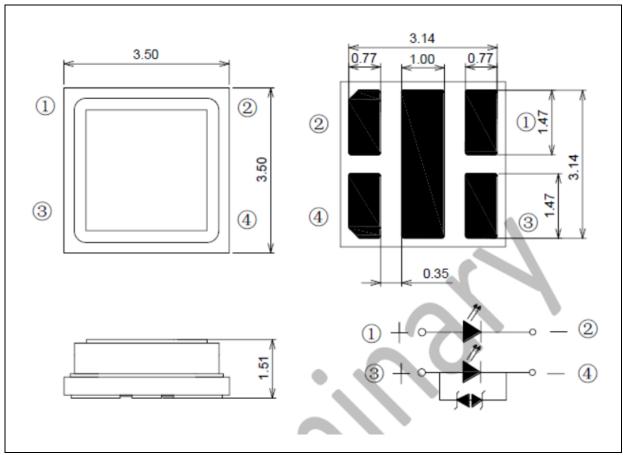






# **OUTLINE DIMENSION:**

# Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

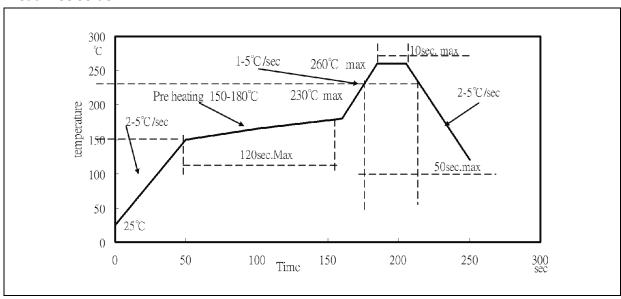






# **RECOMMENDED SOLDERING PROFILE:**

#### Lead-free Solder:



#### Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.

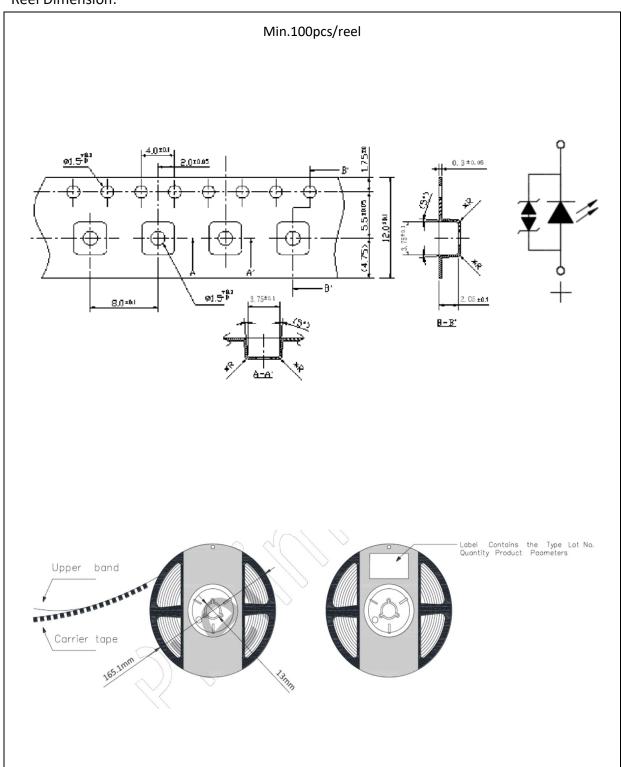






# **PACKING SPECIFICATION:**

## Reel Dimension:









#### PRECAUTIONS OF USE:

## Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

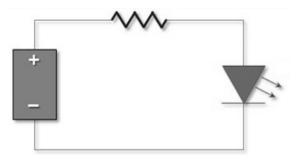
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 65±3°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

## **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

## Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

## ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.







# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	24/09/2020	Datasheet set-up.